

REMARKS

Claims 1, 5, 7-8, 10, and 24 have been amended, Claim 6 has been canceled without prejudice and new Claims 43-44 have been added. More particularly, Claim 1 has been amended to incorporate the features of Claim 6, which accordingly has been canceled without prejudice. Claim 5 has been amended for consistency with the amendment of Claim 1. Claims 7-8 have been amended to depend from Claim 1.

Claim 10 has been amended similarly to Claim 1. Claim 24 has been amended to be in independent form and to include the features of base Claim 10. All claim amendments are directed towards matter of form and thus are unrelated to patentability.

Support for new Claims 43-44 appears in the specification at least at page 11, line 14 to page 14, line 27 and in FIGS. 1-3.

Claims 1-5, 7-12 are novel over Terui (6,225,694).

Claim 1 has been amended to incorporate the features of Claim 6. Accordingly, the rejection of Claim 6 shall be discussed as applied to Claim 1.

The Examiner states:

With regards to claim 6 and 7, Terui disclose **the shield ring comprises upper ground traces** and the ground traces are adjacent to the side of the substrate (see figures 6a-6c). (Office Action, page 3, emphasis added.)

The Examiner's statement is respectfully traversed. Terui teaches an integral single seal ring 4 and the Examiner has failed to callout where Terui teaches or suggests that "the shield ring comprises upper ground traces". Specifically, Terui teaches:

Upon etching at the formation of the interconnections 3, **the copper foil is left even on the**

outer periphery of the substrate 1 as a seal ring 4 as shown in FIG. 3(a). . . . The cap 15 is electrically connected to the substrate 1 through the seal ring 4 . . . (Col. 2, lines 17-53, emphasis added.)

For at least the above reasons, Terui does not teach or suggest:

An electronic component package comprising:
a substrate comprising:
 a first surface;
 a second surface;
 a side;
 a ground shield extending from said first surface to said second surface and adjacent said side;
 a shield ring coupled to said first surface of said substrate, **said shield ring comprising upper ground traces**; and
an electronic component coupled to said first surface,

as recited in amended Claim 1, emphasis added. Accordingly, Claim 1 is allowable over Terui. Claims 2-5, 7-9, and new Claim 43, which depend from Claim 1, are allowable for at least the same reasons as Claim 1.

Claim 10 is allowable over Terui for reasons similar to Claim 1. Claims 11-12, and new Claim 44, which depend from Claim 10, are allowable for at least the same reasons as Claim 10.

For the above reasons, Applicants respectfully request reconsideration and withdrawal of this rejection.

Allowable Subject Matter.

The Examiner states:

Claims 24-29 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. (Office Action, page 4.)

Claim 24 has been rewritten in independent form including the features of base Claim 10. Accordingly, Claim 24 is allowable. Claims 25-29, which depend from Claim 24, are allowable for at least the same reasons as Claim 24.

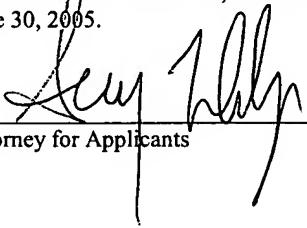
For the above reasons, Applicants respectfully request reconsideration and withdrawal of the objection to Claims 24-29.

CONCLUSION

Claims 1-5, 7-12, 24-29 and 43-44 are pending in the application. For the foregoing reasons, Applicants respectfully request allowance of all pending claims. If the Examiner has any questions relating to the above, the Examiner is respectfully requested to telephone the undersigned Attorney for Applicant(s).

CERTIFICATE OF MAILING

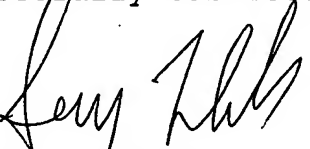
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 30, 2005.



Attorney for Applicants

June 30, 2005
Date of Signature

Respectfully submitted,


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